APPLICATION DATA SHEET

Electronic Version v14 Stylesheet Version v14.0

> Title of Invention

SURFACE-MOUNT-ENHANCED LEAD FRAME AND METHOD FOR FABRICATING SEMICONDUCTOR PACKAGE WITH THE SAME

Application Type:

regular, utility

Attorney Docket Number: 1007-043

Correspondence address:

Customer Number:

22898

22898

Priority Data:

Doc.No: 092105166; Country - TW; Date: 2003-03-11 us-priority-claimed

Inventors Information:

Inventor 1:

Applicant Authority Type:

Inventor

Citizenship:

TW

Given Name:

Te-Haw

Family Name:

LEE

City of Residence:

Taichung

Country of Residence:

TW

Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu,

Address-2 of Mailing Address:

City of Mailing Address:

Taichung

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address:

TW

Phone:

Fax:

E-mail:

Fax:

Inventor 2: **Applicant Authority Type:** Inventor Citizenship: TW Given Name: Kaun-I Family Name: **CHENG** City of Residence: Taichung **Country of Residence:** TW Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu, Address-2 of Mailing Address: City of Mailing Address: **Taichung State of Mailing Address: Postal Code of Mailing Address: Country of Mailing Address:** TW Phone: Fax: E-mail: Inventor 3: **Applicant Authority Type:** Inventor TW Citizenship: Given Name: Yueh-Chiung Family Name: **CHANG** City of Residence: **Taichung** Country of Residence: TW Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu, Address-2 of Mailing Address: City of Mailing Address: **Taichung State of Mailing Address:** Postal Code of Mailing Address: **Country of Mailing Address:** TW Phone:

E-mail:

Inventor 4:

Applicant Authority Type: Inventor

Citizenship: TW

Given Name: Shih-Yao

Family Name: LIU

City of Residence: Taichung

Country of Residence: TW

Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu,

Address-2 of Mailing Address:

City of Mailing Address: Taichung

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address: TW

Phone:

Fax:

E-mail:

Inventor 5:

Applicant Authority Type: Inventor

Citizenship: TW

Given Name: Kun-Ming

Family Name: HUANG

City of Residence: Taichung

Country of Residence: TW

Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu,

Address-2 of Mailing Address:

City of Mailing Address: Taichung

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address: TW

Phone:

US-Request

Fax:

E-mail:

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Assignee 1:

SILICONWARE PRECISION INDUSTRIES CO.,

Organization Name:

LTD.

Address-1 of Mailing Address: No. 123, Sec. 3, Da Fong Road, Tantzu

Address-2 of Mailing Address:

City of Mailing Address:

Taichung

State of Mailing Address:

Postal Code of Mailing

Address:

Country of Mailing Address:

TW

Phone:

Fax:

E-mail: